



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



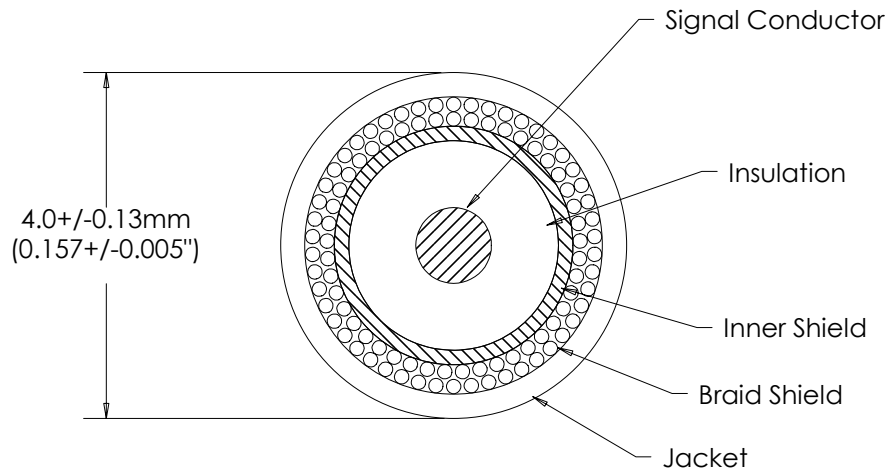
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





CONSTRUCTION

Signal Conductor: 0.036" +/- 0.0003" (0.91 +/- 0.0076mm), Silver Plated Copper per ASTM B-298
 Insulation: FEP per applicable paragraph MIL-DTL-17, 0.117" +/- 0.0015" (3.0 +/- 0.05mm) OD
 Inner Shield: Helically Overlapped Flat Silver Plated Copper per ASTM B-298
 Braid Shield: 40 AWG Silver Plated Copper per ASTM B-298, >85% Coverage
 Overall Shield Diameter: 0.138" +/- 0.002" (3.5 +/- 0.05mm)
 Jacket: FEP in accordance with MIL-DTL-17, Type IX
 Wall Thickness: 0.011" (0.28mm)
 Color: Blue

ELECTRICAL

Impedance: 50 +/- 1 ohms
 Velocity of Propagation: 70%
 Capacitance: 29.0 pF/ft (95 pF/m)

GENERAL

Temperature Rating: -65C to 165C
 Static Bend Radius: 0.5" (12.7mm)
 Dynamic Bend Radius: 1.0" (25.4mm)
 Weight: 28.0 lbs/1000 ft

Freq (GHz)	Attenuation (dB/100ft)	Avg Power (W)
0.5	8	400
1	12	270
2	19	180
4	29	120
8	45	80
12	58	62
18	76	47



This document is the property of TEMP-FLEX. If may not be disclosed, reproduced, or otherwise used without permission.	Rev	DCR	Description	App'd	Date
	8	2974	Update Spec. Template. Add Patent # to General Notes.	KP	6/13/12
	9	3335	Braid Shield P/N Change.	KP	4/2/13
	9	3428	Remove Patent # from General Notes.	J Sanyal	7/8/13